

IEEE HOME | SEARCH IEEE | SHOP | WEB ACCOUNT | CONTACT IEEE

Membership Publications/Services Standards Conferences Careers/Jobs

IEEE Xplore®
RELEASE 1.8Welcome
United States Patent and Trademark OfficeHelp FAQ Terms IEEE Peer Quick Links
Review

» Sea

Welcome to IEEE Xplore®

- ☐ Home
- ☐ What Can I Access?
- ☐ Log-out

Tables of Contents

- ☐ Journals & Magazines
- ☐ Conference Proceedings
- ☐ Standards

Search

- ☐ By Author
- ☐ Basic
- ☐ Advanced

Member Services

- ☐ Join IEEE
- ☐ Establish IEEE Web Account
- ☐ Access the IEEE Member Digital Library

IEEE Enterprise

- ☐ Access the IEEE Enterprise File Cabinet

 Print FormatYour search matched **34** of **1062489** documents.A maximum of **500** results are displayed, **15** to a page, sorted by **Relevance Descending** order.

Refine This Search:

You may refine your search by editing the current search expression or enter a new one in the text box.

Search

☐ Check to search within this result set

Results Key:

JNL = Journal or Magazine **CNF** = Conference **STD** = Standard1 **Application of a CFD tool for system level thermal simulation***Lee, T.; Mahalingam, M.;*

Electronic Components and Technology Conference, 1993. Proceedings., 43rd June 1993

Pages:249 - 255

[\[Abstract\]](#) [\[PDF Full-Text \(620 KB\)\]](#) **IEEE CNF**2 **Thermal design of an optical network unit (ONU) to be implemented an outdoor enclosure***Berger, H.;*

Telecommunications Energy Special, 2000. TELESCon. The Third International Conference on , 7-10 May 2000

Pages:133 - 136

[\[Abstract\]](#) [\[PDF Full-Text \(272 KB\)\]](#) **IEEE CNF**3 **Issues in validating package compact thermal models for natural convection cooled electronic systems***Adams, V.H.; Blackburn, D.L.; Joshi, Y.; Berning, D.W.;*

Semiconductor Thermal Measurement and Management Symposium, 1997. SEMI-THERM XIII., Thirteenth Annual IEEE , 28-30 Jan. 1997

Pages:10 - 23

[\[Abstract\]](#) [\[PDF Full-Text \(1396 KB\)\]](#) **IEEE CNF**4 **Heat transfer in a low aspect ratio horizontal enclosure for laptop computer application***Ortega, A.; Lall, B.S.; Chicci, J.; Aghazadeh, M.; Kiang, B.;*

Semiconductor Thermal Measurement and Management Symposium, 1993.

SEMI-THERM IX., Ninth Annual IEEE , 2-4 Feb. 1993
Pages:42 - 49

[\[Abstract\]](#) [\[PDF Full-Text \(760 KB\)\]](#) IEEE CNF

5 Thermal analysis of two protruding heaters mounted on a substrate plate suspended in an enclosure

Martins, E.B.; Altemani, C.A.C.;

Thermal and Thermomechanical Phenomena in Electronic Systems, 2000. ITH 2000. The Seventh Intersociety Conference on , Volume: 1 , 23-26 May 2000
Pages: 354

[\[Abstract\]](#) [\[PDF Full-Text \(664 KB\)\]](#) IEEE CNF

6 Design and development of a passively cooled remote outdoor cabin

Marongiu, M.J.; Helm, R.; Waiter, K.; Kusha, B.;

Telecommunications Energy Conference, 1998. INTELEC. Twentieth Internatio , 4-8 Oct. 1998
Pages:568 - 575

[\[Abstract\]](#) [\[PDF Full-Text \(536 KB\)\]](#) IEEE CNF

7 Sensitivity of simulated circuit pack thermal performance to geomet arrangement variation

Azar, K.; Develle, S.E.; Manno, V.P.;

Semiconductor Thermal and Temperature Measurement Symposium, 1989. SEMI-THERM V., Fifth Annual IEEE , 7-9 Feb. 1989
Pages:112 - 120

[\[Abstract\]](#) [\[PDF Full-Text \(644 KB\)\]](#) IEEE CNF

8 Minimisation of heat sink mass using mathematical optimisation

Visser, J.A.; de Kock, D.J.; Conradie, F.D.;

Semiconductor Thermal Measurement and Management Symposium, 2000. Sixteenth Annual IEEE , 21-23 March 2000
Pages:252 - 259

[\[Abstract\]](#) [\[PDF Full-Text \(836 KB\)\]](#) IEEE CNF

9 Issues in validating package compact thermal models for natural convection cooled electronic systems

Adams, V.H.; Blackburn, D.L.; Joshi, Y.K.; Berning, D.W.;

Components, Packaging, and Manufacturing Technology, Part A, IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology, IEEE Transactions on] , Volume: 20 , Issue: 4 , Dec. 1997
Pages:420 - 431

[\[Abstract\]](#) [\[PDF Full-Text \(240 KB\)\]](#) IEEE JNL

10 Application of a CFD tool for system-level thermal simulation

Lee, T.Y.T.; Mahalingam, M.;

Components, Packaging, and Manufacturing Technology, Part A, IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology, IEEE Transactions on] , Volume: 17 , Issue: 4 , Dec. 1994
Pages:564 - 572

[\[Abstract\]](#) [\[PDF Full-Text \(736 KB\)\]](#) IEEE JNL

11 **Simulation of large outdoor enclosures using model laws and similitude**
Marongiu, M.J.;
Telecommunications Energy Conference, 1996. INTELEC '96., 18th International Conference on, 6-10 Oct. 1996
Pages:137 - 144

[\[Abstract\]](#) [\[PDF Full-Text \(572 KB\)\]](#) IEEE CNF

12 **Passive cooling of small telecommunication enclosures. Case study of a practical approach**
Porebski, W.; Ulfvengren, R.;
Telecommunications Energy Conference, 1998. INTELEC. Twentieth International Conference on, 4-8 Oct. 1998
Pages:562 - 567

[\[Abstract\]](#) [\[PDF Full-Text \(492 KB\)\]](#) IEEE CNF

13 **Thermal analysis of portable electronic products**
Galloway, J.S.;
Thermal and Thermomechanical Phenomena in Electronic Systems, 1998. ITH '98. The Sixth Intersociety Conference on, 27-30 May 1998
Pages:1 - 7

[\[Abstract\]](#) [\[PDF Full-Text \(556 KB\)\]](#) IEEE CNF

14 **Effect of circuit board parameters on thermal performance of electronic components in natural convection cooling**
Azar, K.; Pan, S.S.; Parry, J.; Rosten, H.;
Semiconductor Thermal Measurement and Management Symposium, 1994. SEMI-THERM X., Proceedings of 1994 IEEE/CPMT 10th, 1-3 Feb. 1994
Pages:32, 163 - 169

[\[Abstract\]](#) [\[PDF Full-Text \(408 KB\)\]](#) IEEE CNF

15 **Effect of system orientation and cooling mechanism on component thermal impedances in an electronic enclosure**
Manno, V.P.; Leisk, G.; Azar, K.;
Semiconductor Thermal and Temperature Measurement Symposium, 1990. SEMI-THERM VI, Proceedings., Sixth Annual IEEE, 6-8 Feb. 1990
Pages:17 - 24

[\[Abstract\]](#) [\[PDF Full-Text \(628 KB\)\]](#) IEEE CNF

[1](#) [2](#) [3](#) [Next](#) [_](#)
